



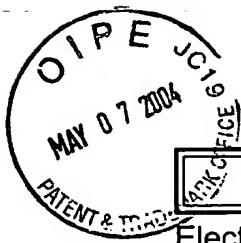
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Electronic Patent Application Submission  
USPTO Use Only

EFS ID: 60605  
Application ID: 10763859  
Title of Invention: SEMICONDUCTOR PACKAGE  
HAVING REDUCED THICKNESS  
First Named Inventor: TAE LEE  
Domestic/Foreign Application: Domestic Application  
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Attorney Docket Number: AMKOR053G




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**TRANSMITTAL**

Electronic Version v1.1  
Stylesheet Version v1.1.0

<b>Title of Invention</b>	<b>SEMICONDUCTOR PACKAGE HAVING REDUCED THICKNESS</b>									
<p>Application Number: 10/763859 </p> <p>Date: 2004-01-23</p> <p>First Named Applicant: TAE HEON LEE</p> <p>Confirmation Number: 8528</p> <p>Attorney Docket Number: AMKOR053G</p>										
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MARK B. GARRED Registered Number: 34,823	/mbg/	Attorney								
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Documents being submitted	Files									
us-ids	ids6-usidst.xml									
	us-ids.dtd									
	us-ids.xsl									
<b>Comments</b>										



## ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

### Title of Invention

### SEMICONDUCTOR PACKAGE HAVING REDUCED THICKNESS

Application Number: 10/763859  
Confirmation Number: 8528  
First Named Applicant: TAE LEE  
Attorney Docket Number: AMKOR053G  
Art Unit: 2811



Search string: ( 6348726 or 6355502 or 6369447 or 6369454  
or 6373127 or 6380048 or 6384472 or 6388336  
or 6395578 or 6410979 or 6400004 or 6414385  
or 6420779 or 6429508 or 6437429 or 6444499  
or 6448633 or 6452279 or 6459148 or 6464121  
or 6476469 or 6476474 or 6482680 or 6498099  
or 6498392 or 6507096 or 6507120 or 6534849  
or 6545332 or 6545345 or 6559525 or 6566168  
or 6583503 or 6667546 ).pn.

### US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
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Signature

Examiner Name	Date